



The **DCS1-050518** piezoelectric stack consists of multiple chips which are bonded via epoxy. It offers a maximum displacement of 19.0  $\mu$ m. The red wire of the electrode serves as the positive terminal (+), and the black wire is the negative terminal (-).



DCS1-050518

## **Performance Parameters**

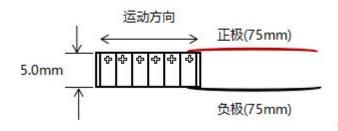
Drive Voltage Range	-15∼75 V	Capacitance	6.5µF ± 15%
Displacement (Free Stroke) at 150 V	$19.0~\mu\text{m}\pm15\%$	Dissipation Factor	<2.0%
Hysteresis	<15%	Resonant Frequency	70kHZ
Stiffness	59 N/μm	Blocking Force at 150 V	1000N
Curie Temp <mark>erature</mark>	230 °C	Operating Temperature	-25 ∼ 130 °C
Product Size	L: 5.0mm	Outer Dimensions	L: 5.2 ± 0.2mm
	W: 5.0mm		$W{:}~7.2 \pm 0.2 mm$
	H: 18.0mm		$H{:}\ 18.0 \pm 0.1 mm$

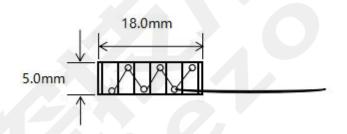
- All specifications are quoted at 25°C, unless otherwise stated.
- The displacement may vary slightly for different loads, and the maximum displacement occurs when used with the recommended load.



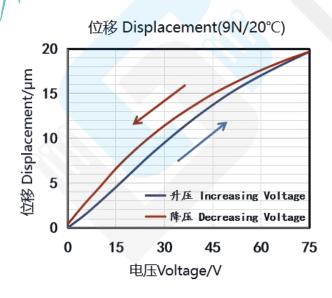


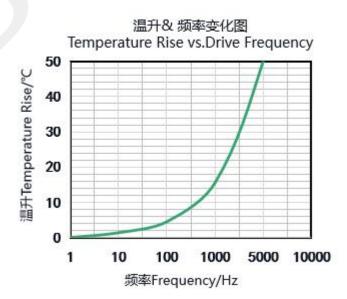
# Product Size





## **Performance Curve**





• These temperature rises were measured after applying a sine-wave drive voltage ranging from 0 to 75V at the specified frequency for 10 minutes.

Guangdong DCpiezo Technology Co., Ltd.





## **Matters Needing Attention**

#### 1. Storage Conditions & Precautions:

Temperature: <50 °C, Humidity: <40%Rh. Avoid impact and compression. Store in vacuum-sealed bags for long-term preservation. When not in use, connect to a resistive discharge ( $\geq$ 100k $\Omega$ ) or short-circuit (for low-capacitance ceramics).

### 2. Operating Conditions & Precautions:

Temperature: Maximum operating temperature  $\leq 130^{\circ}$ C (preferably  $< 60^{\circ}$ C). Add heat dissipation measures if temperature exceeds  $80^{\circ}$ C.

Humidity: <50%Rh. In high-humidity environments, preheat at low voltage before use to avoid creepage discharge.

Dust Avoidance: Dust adhesion on ceramic surfaces may reduce insulation resistance.

Clearance: Maintain a gap >1.6mm between ceramics and other conductors.

Safety: Do not immerse piezoelectric stacks in organic solvents or expose to flammable gases/liquids.

#### 3. Assembly Precautions:

Polarity: Red wire = positive (+), black wire = negative (-). Reverse polarity may cause mechanical failure.

Handling: Handle with care to avoid impact. Wear gloves to prevent oil contamination.

Fit Tolerance: Assemble with clearance fit first, then tighten. Avoid interference fit to prevent ceramic compression.

Electrostatic Protection: Maintain >1.6mm gap between ceramics and metal parts to avoid static discharge.

Adhesive Bonding: Ensure flat bonding surfaces and remove excess glue to minimize contamination.

Soldering: Limit contact time under high temperature to <1 second to protect ceramics and coatings.

High-Temperature Assembly: Control temperature <120 $^{\circ}$ C to prevent depolarization, adhesive failure, or coating damage.

#### 4. Preload Instructions:

Load Application: Apply external load to the center of the stack or distribute uniformly on the Guangdong DCpiezo Technology Co., Ltd.





mounting surface. Ensure contact surfaces are flat and smooth.

Force Direction: Piezoelectric stacks can only withstand axial forces. Shear or torsional forces may cause mechanical failure.

Preload Force: Preload should not exceed 40% of maximum blocking force, and its direction must align with the motion axis to minimize shear stress.

